

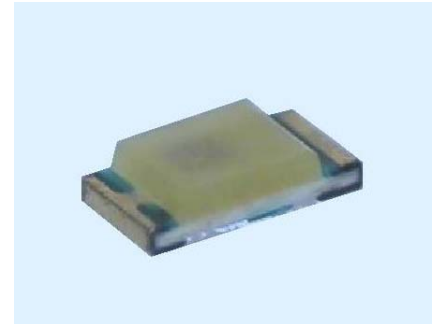
Technical Data Sheet

0603 Package Chip LED (0.4mm Height)

GT-197

Features

- Package in 8mm tape on 7" diameter reel.
- Compatible with automatic placement equipment.
- Compatible with infrared and vapor phase reflow solder process.
- Mono-color type.
- Pb-free.
- The product itself will remain within RoHS compliant version.



Descriptions

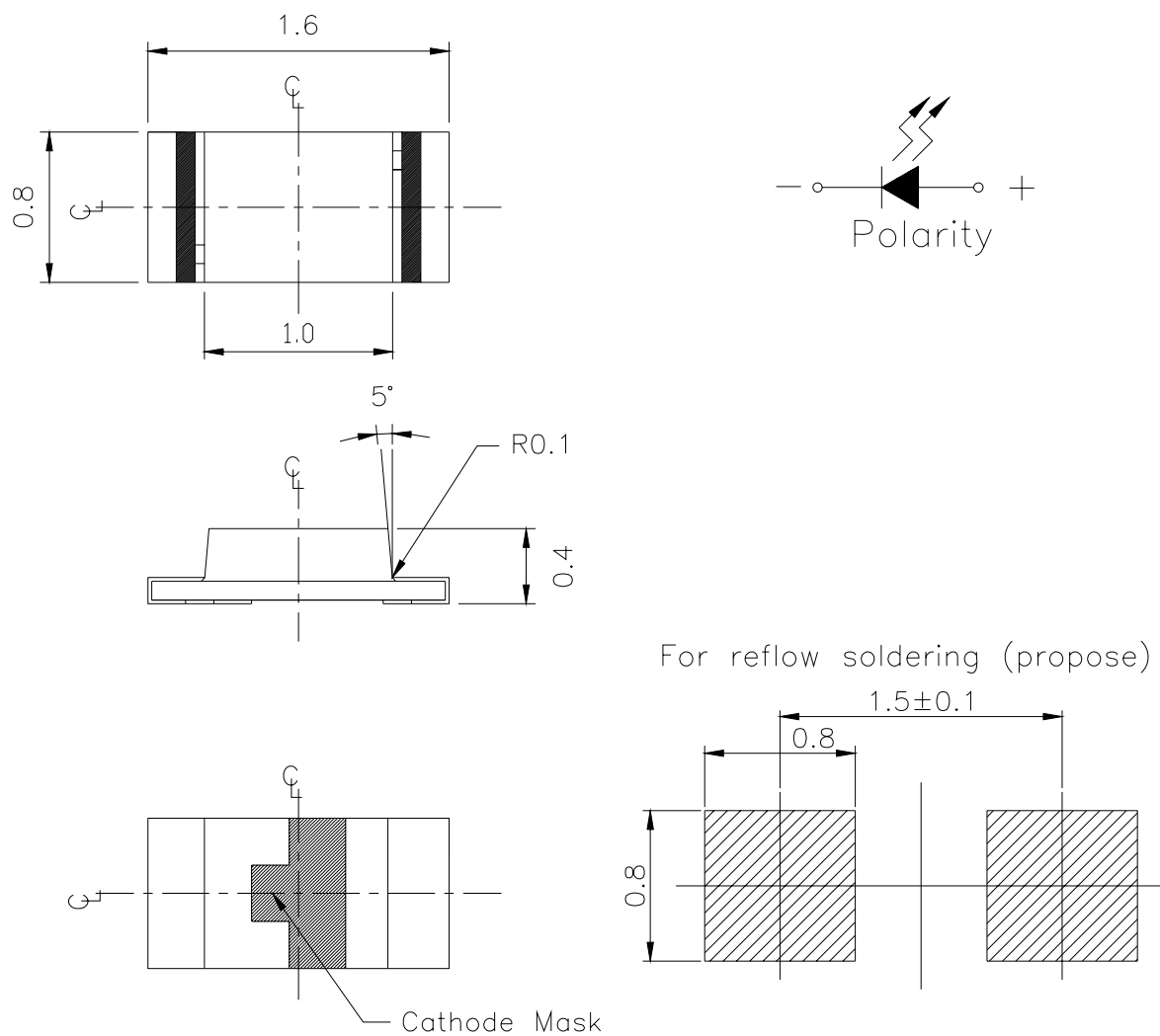
- The GT-197 SMD LED is much smaller than lead frame type components, thus enable smaller board size, higher packing density, reduced storage space and finally smaller equipment to be obtained.
- Besides, lightweight makes them ideal for miniature applications. etc.

Applications

- Backlighting in dashboard and switch.
- Telecommunication: indicator and backlighting in telephone and fax.
- Flat backlight for LCD, switch and symbol.
- General use.

Device Selection Guide

Chip		Lens Color
Material	Emitted Color	
InGaN	Pure White	Yellow Diffused

Package Outline Dimensions

Note: The tolerances unless mentioned is ± 0.1 mm , Unit = mm

Absolute Maximum Ratings (Ta=25°C)

Parameter	Symbol	Rating	Unit
Reverse Voltage	V _R	5	V
Forward Current	I _F	25	mA
Operating Temperature	T _{opr}	-40 ~ +85	°C
Storage Temperature	T _{stg}	-40 ~ +90	°C
Soldering Temperature	T _{sol}	260 (for 5 seconds)	°C
Electrostatic Discharge(HBM)	ESD	150	V
Power Dissipation	P _d	110	mW
Peak Forward Current (Duty 1/10 @1KHz)	I _{FP}	100	mA
Soldering Temperature	T _{sol}	Reflow Soldering : 260 °C for 10 sec. Hand Soldering : 350 °C for 3 sec.	

Electro-Optical Characteristics (Ta=25°C)

Parameter	Symbol	Min.	Typ.	Max.	Unit	Condition
Luminous Intensity	I _v	18	-----	112	mcd	I _F =5mA
		-----	200	-----		I _F =20mA
Viewing Angle	2 θ 1/2	-----	130	-----	deg	I _F =5mA
Forward Voltage	V _F	2.70	-----	3.30	V	I _F =5mA
		-----	3.3	-----		I _F =20mA
Reverse Current	I _R	-----	-----	50	μ A	V _R =5V

Notes:**1.Tolerance of Luminous Intensity ±10%****2.Tolerance of Forward Voltage ±0.1V**

Bin Range Of Luminous Intensity

Bin	Min	Max	Unit	Condition
M	18	28.5	mcd	I _F =5mA
N	28.5	45		
P	45.0	72		
Q	72.0	112		

Bin Range Of Forward Voltage

Bin	Min	Max	Unit	Condition
29	2.70	2.80	V	I _F =5mA
30	2.80	2.90		
31	2.90	3.00		
32	3.00	3.10		
33	3.10	3.20		
34	3.20	3.30		

Notes:

- 1.Tolerance of Luminous Intensity $\pm 10\%$**
- 2.Tolerance of Forward Voltage $\pm 0.1V$**

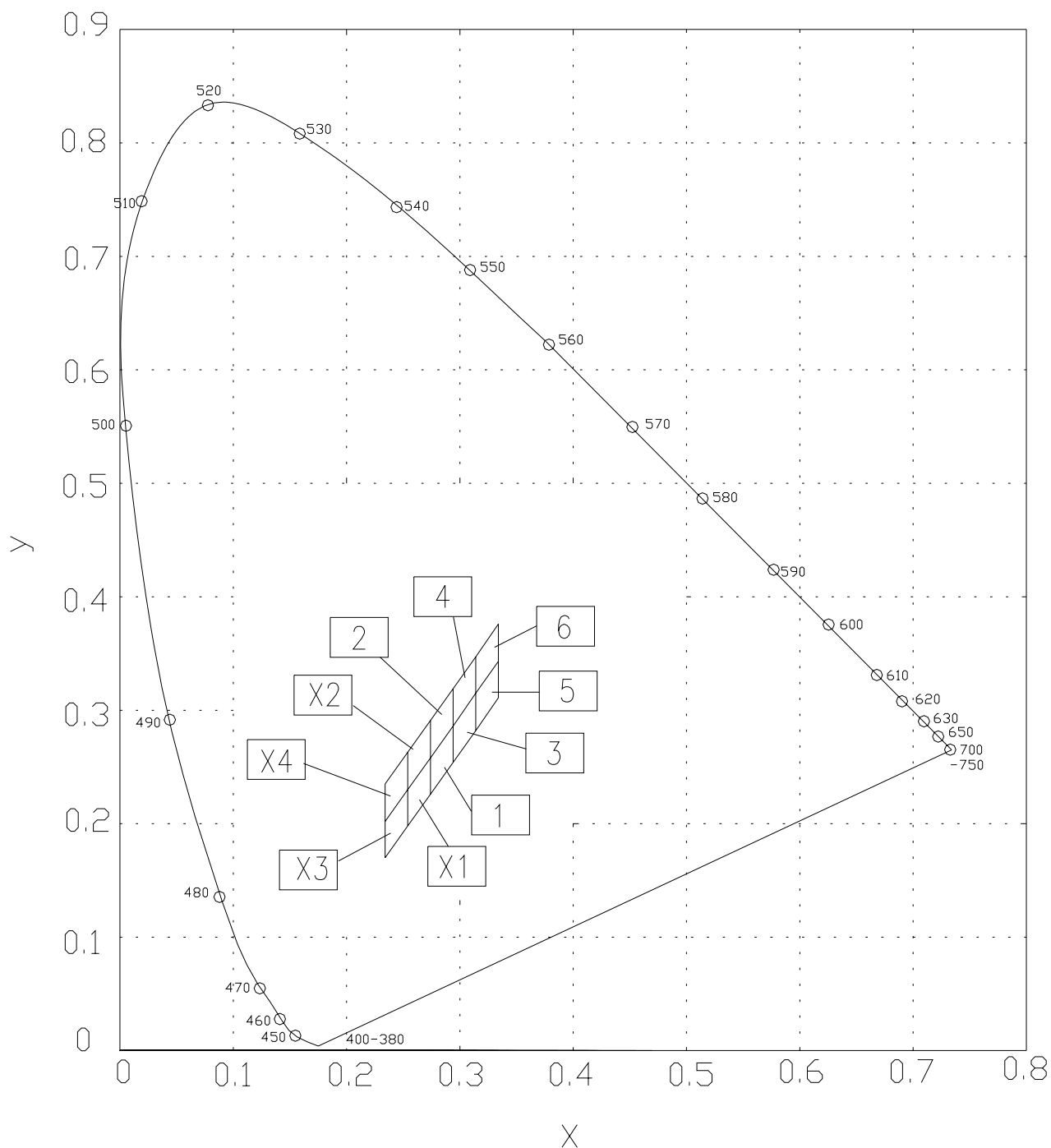
Chromaticity Coordinates Specifications for Bin GradingTest condition: $I_F=5\text{mA}$

Bin Code	CIE_x	CIE_y	Bin Code	CIE_x	CIE_y
X4	0.234	0.202	1	0.274	0.226
	0.234	0.235		0.274	0.258
	0.254	0.263		0.294	0.286
	0.254	0.230		0.294	0.254
X3	0.234	0.170	2	0.274	0.258
	0.234	0.202		0.274	0.291
	0.254	0.230		0.294	0.319
	0.254	0.198		0.294	0.286
X2	0.254	0.230	3	0.294	0.254
	0.254	0.263		0.294	0.286
	0.274	0.291		0.314	0.315
	0.274	0.258		0.314	0.282
X1	0.254	0.198	4	0.294	0.286
	0.254	0.230		0.294	0.319
	0.274	0.258		0.314	0.347
	0.274	0.226		0.314	0.315
			5	0.314	0.282
				0.314	0.315
				0.334	0.343
				0.334	0.311
			6	0.314	0.315
				0.314	0.347
				0.334	0.376
				0.334	0.343

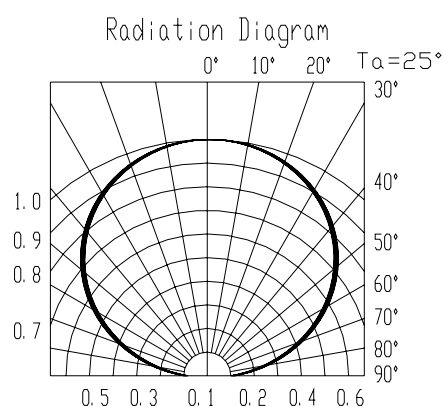
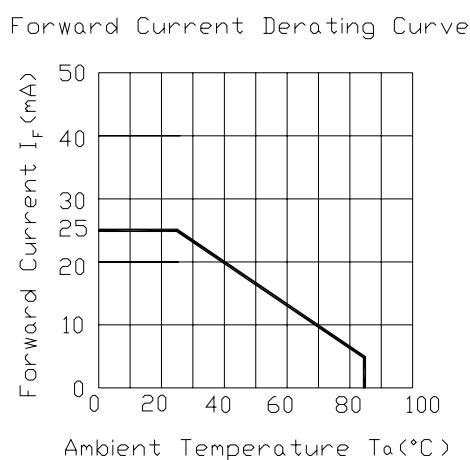
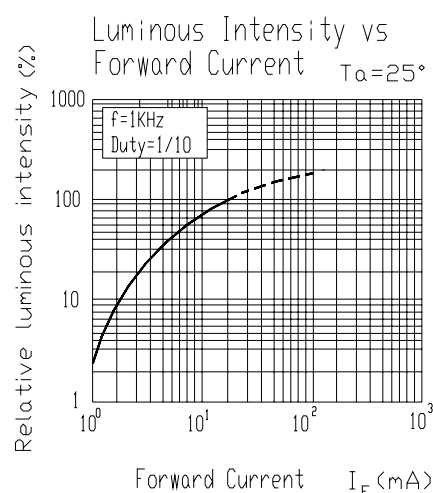
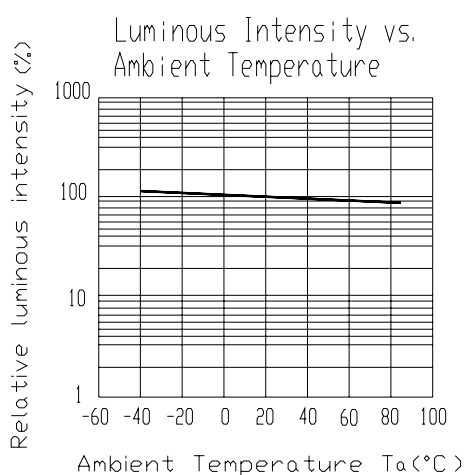
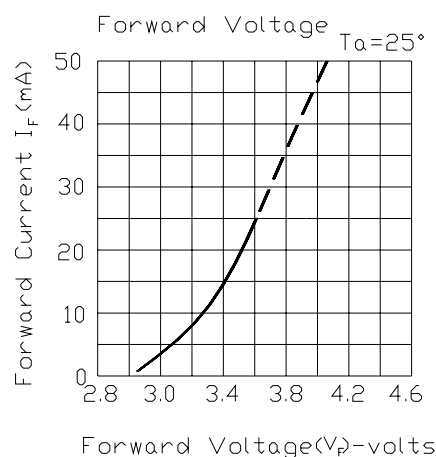
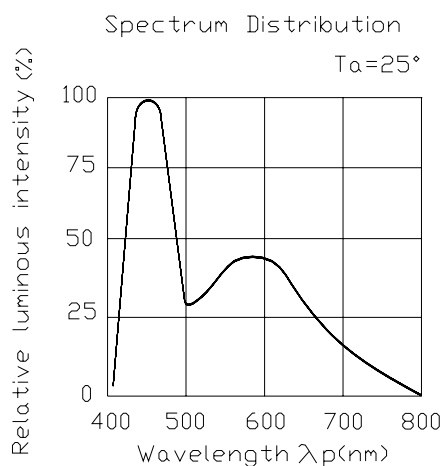
Notes:

1. The C.I.E. 1931 chromaticity diagram (tolerance ± 0.01).

CIE Chromaticity Diagram



Typical Electro-Optical Characteristics Curves

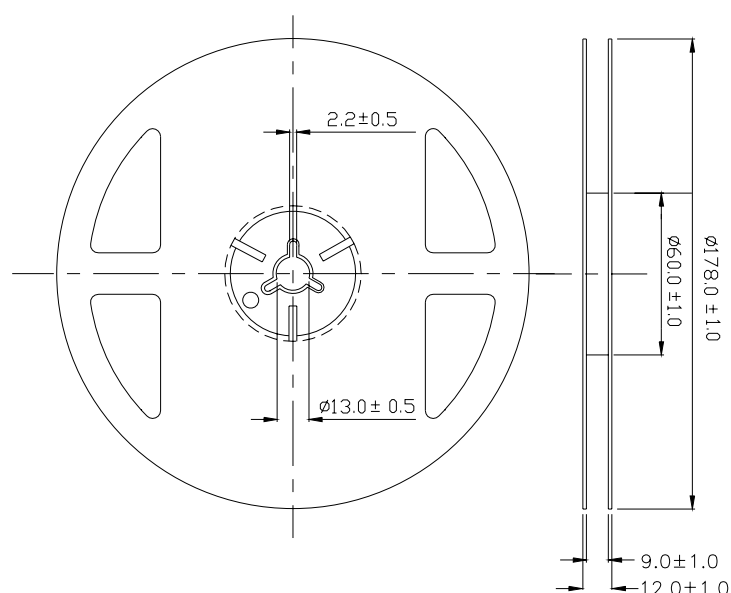


Label explanation

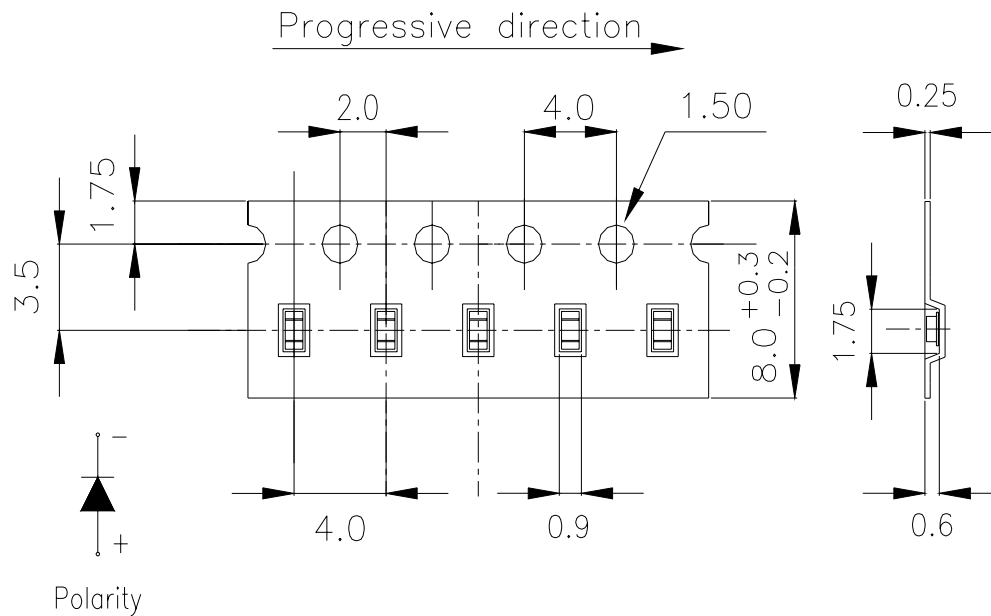
CAT: Luminous Intensity Rank HUE: Chromaticity Coordinates REF: Forward Voltage Rank

<i>CPN :</i> <i>GT-XXX</i> <i>QTY:XXXX</i>  <i>P/N:XXXXXXXXXX</i>  <i>LOT NO:XXXXXXXX</i>  <i>CAT: HUE: REF:</i>		
---	--	--

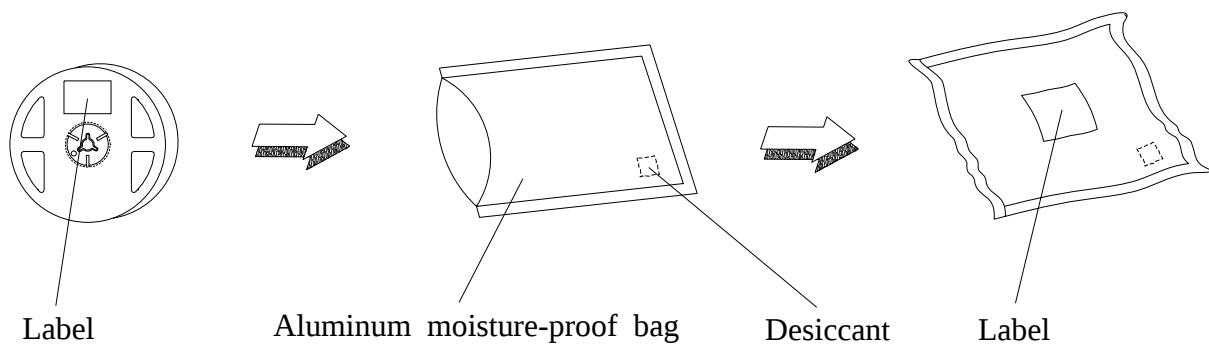
Reel Dimensions



Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$,Unit = mm

Carrier Tape Dimensions: Loaded quantity 3000 PCS per reel

Note: The tolerances unless mentioned is $\pm 0.1\text{mm}$, Unit = mm

Moisture Resistant Packaging

Reliability Test Items and Conditions

The reliability of products shall be satisfied with items listed below.

Confidence level : 90%

LTPD : 10%

No.	Items	Test Condition	Test Hours/Cycles	Sample Size	Ac/Re
1	Reflow Soldering	Temp. : 260°C±5°C Min. 5 sec.	6 Min.	22 PCS.	0/1
2	Temperature Cycle	H : +100°C 15min ∫ 5 min L : -40°C 15min	300 Cycles	22 PCS.	0/1
3	Thermal Shock	H : +100°C 5min ∫ 10 sec L : -10°C 5min	300 Cycles	22 PCS.	0/1
4	High Temperature Storage	Temp. : 100°C	1000 Hrs.	22 PCS.	0/1
5	Low Temperature Storage	Temp. : -40°C	1000 Hrs.	22 PCS.	0/1
6	DC Operating Life	I _F = 20 mA / 25°C	1000 Hrs.	22 PCS.	0/1
7	High Temperature / High Humidity	85°C/85%RH	1000 Hrs.	22 PCS.	0/1

Precautions For Use

1. Over-current-proof

Customer must apply resistors for protection, otherwise slight voltage shift will cause big current change (Burn out will happen).

2. Storage

2.1 Do not open moisture proof bag before the products are ready to use.

2.2 Before opening the package: The LEDs should be kept at 30°C or less and 90%RH or less.

2.3 After opening the package: The LED's floor life is 1 year under 30 deg C or less and 60% RH or less.

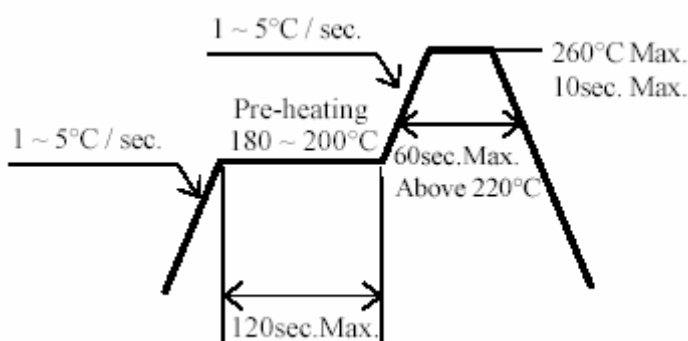
If unused LEDs remain, it should be stored in moisture proof packages.

2.4 If the moisture absorbent material (silica gel) has faded away or the LEDs have exceeded the storage time, baking treatment should be performed using the following conditions.

Baking treatment : 60±5°C for 24 hours.

3. Soldering Condition

3.1Pb-free solder temperature profile



3.2 Reflow soldering should not be done more than two times.

3.3 When soldering, do not put stress on the LEDs during heating.

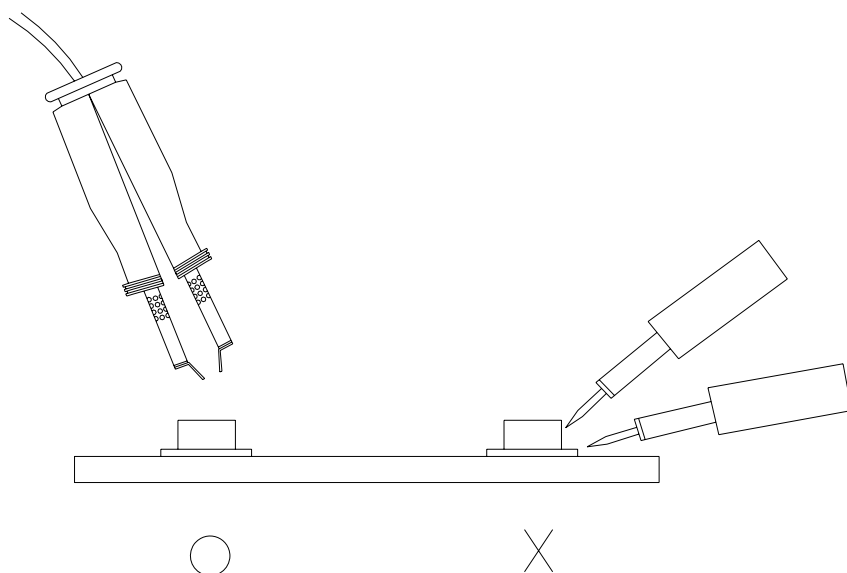
3.4 After soldering, do not warp the circuit board.

4. Soldering Iron

Each terminal is to go to the tip of soldering iron temperature less than 350°C for 3 seconds within once in less than the soldering iron capacity 25W. Leave two seconds and more intervals, and do soldering of each terminal. Be careful because the damage of the product is often started at the time of the hand solder.

5. Repairing

Repair should not be done after the LEDs have been soldered. When repairing is unavoidable, a double-head soldering iron should be used (as below figure). It should be confirmed beforehand whether the characteristics of the LEDs will or will not be damaged by repairing.



6. Handling Indications

During processing, mechanical stress on the surface should be minimized as much as possible. Sharp objects of all types should not be used to pierce the sealing compound